MA3J7410G

Silicon epitaxial planar type

For high speed switching For wave detection

Features

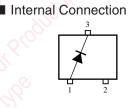
- Mini type of MA3X704A
- Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R

Absolute Maximum R			
Parameter	Symbol	Rating	Unit
Reverse voltage	VR	30	V
Maximum peak reverse voltage	V _{RM}	30	V
Forward current	I _F	30	mA
Peak forward current	I _{FM}	150	mA
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C



- Code
- SMini3-F2
- Pin Name
- 1: Anode
- 2: N.C.
- 3: Cathode

Marking Symbol: M1L



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

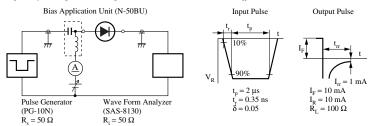
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$	- Al	J.	0.4	V
	V _{F2}	I _F = 30 mA	2.2		1.0	
Reverse current	I _R	$V_{\rm R} = 30 {\rm V}$			300	nA
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$		1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

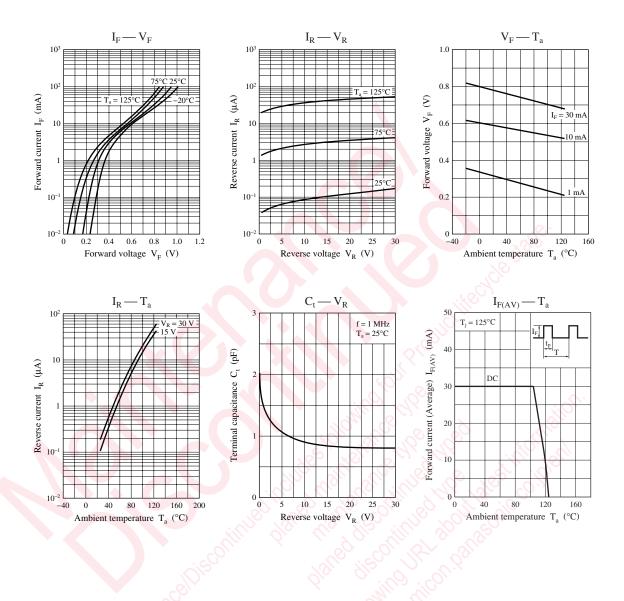
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

4.*: trr measurement circuit

3. Absolute frequency of input and output is 2 GHz.

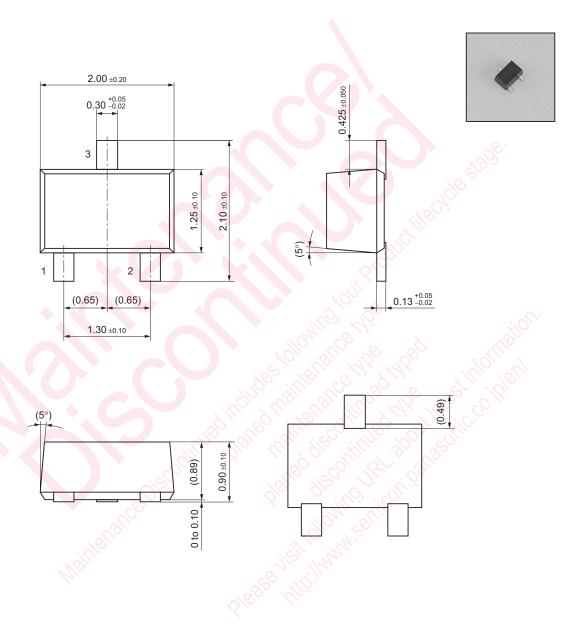


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SMini3-F2

Unit: mm



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